

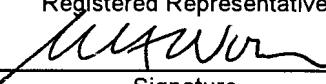
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H Chapman
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William A. Webb, Reg. No. 28,277

Name of Applicant, assignee or
Registered Representative


Signature



Our Case No. 7103/30

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Homayoun Talieh and David E. Weldon)
Serial No.: 08/853,323) Examiner: George Nguyen
Filing Date: May 8, 1997) Group Art Unit No. 3203
For Linear Polisher and Method for)
Semiconductor Wafer Planarization)

RECEIVED

JUN - 8 1998

AMENDMENT

GROUP 3200

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Please enter the following amendments in response to the Office Action of
February 26, 1998.

In the Claims

Please cancel Claims 1-22, 33 and 35 without prejudice, please amend Claims
32 and 34 as follows, and please enter new Claims 36-43 as follows:

C 1 32. (Amended) A polishing pad assembly for polishing a semiconductor

06/05/1998 AT Wafer, ~~06/05/1998~~ assembly comprising:

01 FC:102

328.00-0P

